## **60V N-Channel DTMOS**

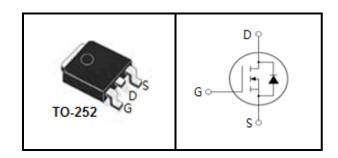
#### **FEATURES**

- Trench Power DTMOS technology
- Low R<sub>DS(ON)</sub>
- Low Gate Charge
- Optimized for fast-switching applications

#### **APPLICATIONS**

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

Device Marking and Package Information				
Device	Package	Marking		
TSD12N06AT	TO-252	12N06AT		





<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted				
Parameter	Symbol	Value	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	60	V	
Continuous Drain Current	I <sub>D</sub>	60	Α	
Pulsed Drain Current (note1)	I <sub>DM</sub>	240	Α	
Gate-Source Voltage	$V_{GSS}$	±20	V	
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	65	mJ	
Avalanche Current (note1)	I <sub>AS</sub>	36	Α	
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	56.5	W	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+175	°C	

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	1.7	000
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	50	°C/W



Specifications T <sub>J</sub> = 25°C, unless otherwise noted							
Parameter	Symbol Test Conditions		Value	1			
			Min.	Тур.	Max.		
Static			1				
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	60			V	
Zero Gate Voltage Drain Current	,	$V_{DS} = 60V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1		
Zero Gate Voltage Drain Guirent	I <sub>DSS</sub>	$V_{DS} = 60V, V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	μA	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 20V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1		2.5	V	
	D	$V_{GS} = 10V, I_D = 20A$		6.5	9	mΩ	
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	$V_{GS} = 4.5V, I_{D} = 20A$		10.7	13.5		
Forward Transconductance (Note3)	g <sub>fs</sub>	$V_{DS} = 5V, I_{D} = 20A$		85		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>	V 0V		2455		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 30V,$		240			
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		34			
T	Q <sub>g</sub> (10V)			45		nC	
Total Gate Charge	Q <sub>g</sub> (4.5V)	$V_{DD} = 30V, I_{D} = 20A,$ $V_{GS} = 10V$		24			
Gate-Source Charge	$Q_{gs}$			6.8			
Gate-Drain Charge	$Q_{gd}$			11.5			
Turn-on Delay Time	t <sub>d(on)</sub>	$V_{DD} = 30V$ , $I_D = 20A$ , $R_G = 3\Omega$		8			
Turn-on Rise Time	t <sub>r</sub>			3		ns	
Turn-off Delay Time	t <sub>d(off)</sub>			25			
Turn-off Fall Time	t <sub>f</sub>			4			
Drain-Source Body Diode Characteris	stics		•	•			
Continuous Body Diode Current	Is	$T_{\rm C} = 25^{\rm o}{\rm C}$			46	А	
Pulsed Diode Forward Current	I <sub>SM</sub>				138		
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = 1A$ , $V_{GS} = 0V$		0.72	1	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20A,		25		ns	
Reverse Recovery Charge	Q <sub>rr</sub>	$di_{F}/dt = 500A/\mu s$		110		nC	

#### Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2.  $I_{AS}$  = 36A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  1%



### **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted

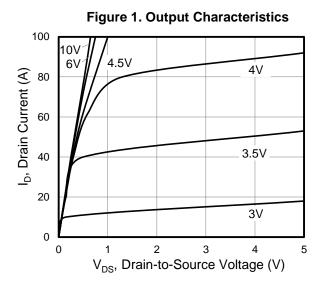


Figure 3. On-Resistance vs. Drain Current

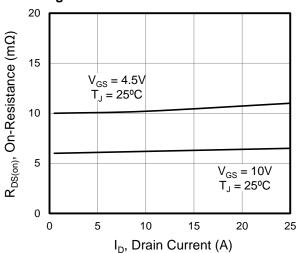


Figure 5. Gate Charge

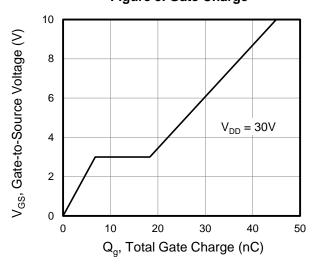


Figure 2. Transfer Characteristics

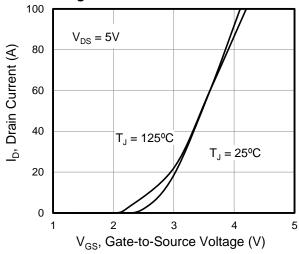


Figure 4. Capacitance

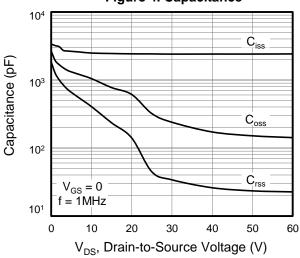
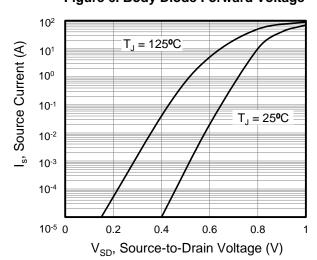


Figure 6. Body Diode Forward Voltage





## **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

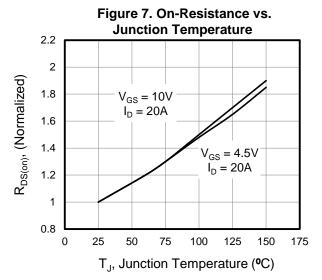
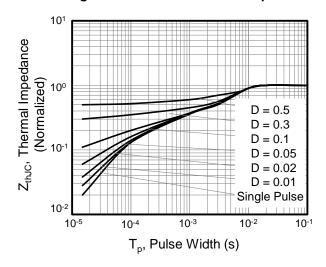


Figure 9. Transient Thermal Impedance



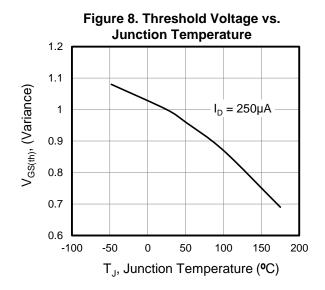


Figure A: Gate Charge Test Circuit and Waveform

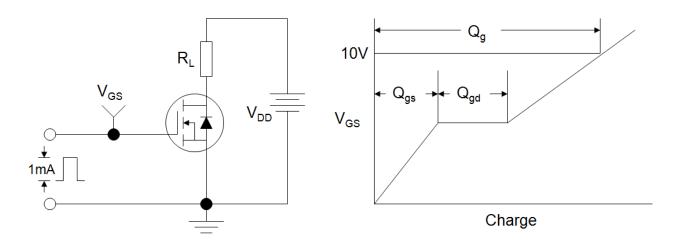


Figure B: Resistive Switching Test Circuit and Waveform

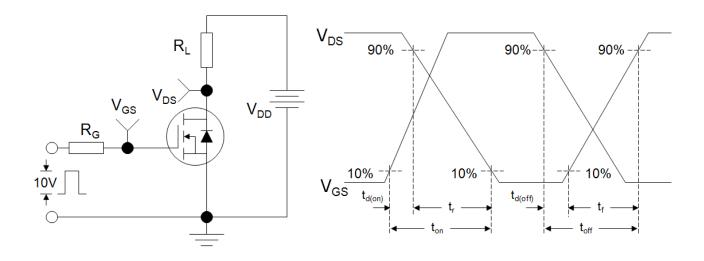
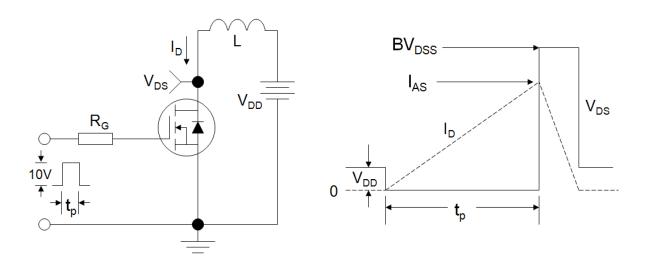
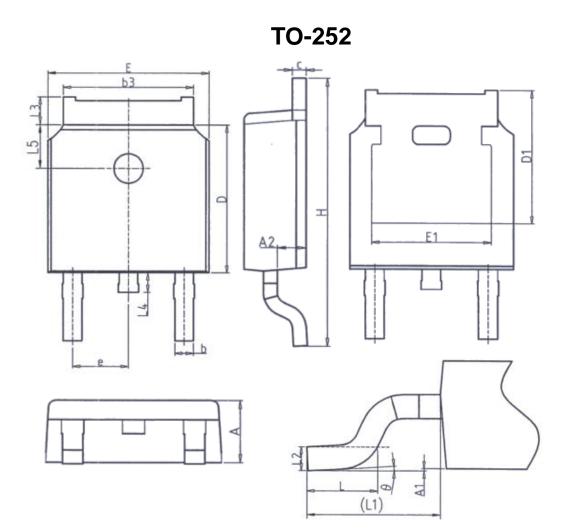


Figure C: Unclamped Inductive Switching Test Circuit and Waveform







Unit: mm			
Symbol	Min.	Max.	
Α	2. 20	2. 40	
A1	0.00	0. 20	
A2	0. 97	1. 17	
b	0. 68	0. 90	
b3	5. 20	5. 50	
С	0. 43	0. 63	
D	5. 98	6. 22	
D1	D1 5. 30REF		
E	6. 40	6. 80	
E1	4. 63	_	

Unit: mm			
Symbol	Min.	Max.	
е	2. 286BSC		
Н	9. 40	10.50	
L	1. 38	1. 75	
L1	2. 90REF		
L2	0. 51BSC		
L3	0.88	1. 28	
L4	- 1.00		
L5	1. 65	1. 95	
θ	0°	8°	



#### **Disclaimer**

All product specifications and data are subject to change without notice.

For documents and material available from this datasheet, Wuxi Unigroup does not warrant or assume any legal liability or responsibility for the accuracy, completeness of any product or technology disclosed hereunder.

No license, express or implied, by estoppels or otherwise, to any intellectual property rights is granted by this document or by any conduct of Wuxi Unigroup.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling Wuxi Unigroup products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Wuxi Unigroup for any damages arising or resulting from such use or sale.

Wuxi Unigroup disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Wuxi Unigroup's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

Wuxi Unigroup Microelectronics CO., LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all Wuxi Unigroup products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

Information (including circuit diagrams and circuit parameters) herein is for example only. It is not guaranteed for volume production. Wuxi Unigroup believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.